

Amendments to the Specification

Page 5, please replace the heading at line 19 with the following rewritten heading:

Disclosure of Summary of the Invention

Page 6, please replace the paragraph spanning lines 2-16 with the following rewritten paragraph:

In order to achieve the above objects, the present invention provides a substrate holding apparatus comprising: a substrate holder, provided with a first sealing member, for supporting a substrate by bringing a peripheral portion of a surface to be processed of the substrate into contact with the first sealing member; and a substrate pressing section for lowering relative to the substrate holder so as to press the substrate held by the substrate holder downward, thereby bringing the first sealing member into pressure contact with the substrate; ~~wherein the substrate.~~ The substrate pressing section is provided with a second ring-shaped sealing member which, when the substrate pressing section lowers relative to the substrate holder, makes pressure contact with an upper surface of a ring-shaped holding section of the substrate holder, thereby sealing the peripheral region of the substrate pressing section.

Page 7, please replace the paragraph spanning line 31 through page 8, line 10 with the following rewritten paragraph:

According to this embodiment, when holding a substrate by the substrate holding apparatus, the substrate is pressed downward by the pressing pins through the elastic forces of the elastic bodies. If bending occurs in the first sealing member, the degree of pressing (degree of contraction) can be adjusted by the pressing pins according to the degree of the bending, thereby preventing the formation of an empty space between the faces being sealed. Further, if the substrate is sticking to the substrate pressing section when detaching the substrate from the substrate pressing section after the completion of processing, the substrate can be securely detached from the substrate pressing section through the elastic forces of the elastic bodies.

Page 9, please replace the paragraph spanning line 22 through page 10, line 1 with the following rewritten paragraph:

The present invention also provides another substrate holding apparatus comprising: a substrate holding section for supporting a substrate with its front surface facing downward; and an attraction head provided with an attraction seal for attracting and holding the substrate supported by the substrate holding section while sealing a peripheral portion of the back surface of the substrate in a ring; ~~wherein the~~ ring. The substrate holding section is provided with a plurality of pressing mechanisms, disposed at locations along the circumferential direction of the substrate holding section, for contacting a peripheral portion of the front surface of the substrate supported by the substrate holding section and pressing the substrate against the attraction head.

Page 10, please replace the paragraph spanning lines 24-28 with the following rewritten paragraph:

Preferably, the movable claw is supported vertically pivotably by a pivot shaft and disposed along the diametral diametrical direction of the substrate holding section, biased downwardly by an elastic body on the outer side of the pivot shaft, and makes contact with a peripheral portion of the front surface of the substrate on the inner side of the pivot shaft.

Page 11, please replace the paragraph spanning lines 3-14 with the following rewritten paragraph:

The present invention also provides still another substrate holding apparatus comprising: a substrate holding section for supporting a substrate with its front surface facing downward; and an attraction head provided with an attraction seal for attracting and holding the substrate supported by the substrate holding section while sealing a peripheral portion of the back surface of the substrate in a ring; ~~wherein the~~ ring. The substrate holding section includes a base section, and a substrate support section for supporting the substrate, disposed at a given distance from the base section and tiltably coupled to the base section by a coupling section provided at a peripheral portion of the substrate support section.

Page 12, please replace the paragraph spanning lines 15-31 with the following rewritten paragraph:

The present invention also provides another substrate processing apparatus comprising: a substrate holding apparatus for holding a substrate; and a processing tank for bringing a surface to be processed of a substrate, held by the substrate holding apparatus, into contact with a processing liquid stored in the processing tank. The substrate holding apparatus comprises a substrate holding section for supporting the substrate with its front surface facing downward, and an attraction head provided with an attraction seal for attracting and holding the substrate supported by the substrate holding section while sealing the peripheral portion of the back surface of the substrate in a ~~ring, wherein the ring.~~ The substrate holding section is provided with a plurality of pressing mechanisms, disposed at locations along the circumferential direction of the substrate holding section, for contacting a peripheral portion of the front surface of the substrate supported by the substrate holding section and pressing the substrate against the attraction head.

Page 15, please replace the heading at line 21with the following rewritten heading:

~~Best Mode for Carrying Out~~ Detailed Description of the Invention

Page 24, please replace the paragraph spanning lines 10-32 with the following rewritten paragraph:

First, the substrate holding apparatus 80 is set at a position above the processing tank 10, as shown in FIGS. 2A and 2B, and the substrate pressing section 85 is set at a raised portion within the substrate holding apparatus 80, as shown in FIG. 5. A substrate W, which is held ~~in~~ face down by the vacuum hand R of the robot (see FIG. 5), is inserted into the substrate holder 84 and the vacuum attraction of the vacuum hand R is released, thereby placing the substrate W on the first ring-shaped sealing member 92 having a diameter smaller by several mm than the diameter of the substrate W. The vertical drive mechanism 911 is then driven to lower the substrate pressing section 85 so that, as shown in FIGS. 6B and 7, the pressing pins 165 are pressed against a peripheral region of the upper surface of the substrate W whereby a peripheral region of the lower surface (surface to be processed) of the substrate W is pressed against the first sealing member 92, thereby fixing the substrate W. The first sealing member 92 is brought

into pressure contact with the peripheral region of the substrate W to seal the peripheral region of the substrate W, and the second sealing member 170 is brought into pressure contact with the upper surface of the holding section 82 of the substrate holder 84 to seal the peripheral region of the substrate pressing section 85.

Page 31, please replace the paragraph spanning lines 23-32 with the following rewritten paragraph:

FIG. 11 is an enlarged cross-sectional view of the main portion of the attraction head 584. As shown in FIGS. 10 and 11, the attraction head 584 comprises a generally circular support 588 having in its interior a vacuum supply line (vacuum/gas supply line) 586, a ring-shaped substrate attraction seal 590 mounted to the lower surface of the support 588, and a plurality of pushers 592 mounted inside the ring-shaped substrate attraction seal 590. Air vent portions 594 (see FIG. 10) comprised of openings, which penetrate up and down, ~~is-~~are provided in the support 588.

Page 33, please replace the paragraph spanning line 33 through page 34, line 10 with the following rewritten paragraph:

In each housing portion 680 of the guide support 672 is housed an elastic body 686, comprised of a helical spring, whose lower surface is in contact with the bottom wall of the housing portion 680, ~~while and~~ whose upper surface is in contact with the lower surface of a collar 684 which is mounted to the upper surface of the guide bolt 678 by a bolt 682. Thus, the substrate support section 662, at the opposite portions in the radial direction, is elastically coupled to the base section 660 through the elastic force of the elastic body (helical spring) 686 so that the substrate support section 662 can tilt with respect to the base section 660.

Page 34, please replace the paragraph spanning line 26 through page 35, line 7 with the following rewritten paragraph:

FIG. 14 is an exploded perspective view showing the pressing mechanism 664, and FIG. 15 is an enlarged sectional view showing the main portion of the pressing mechanism 664 together with the attraction seal 590 of the attraction head 584. As shown in FIGS. 12, 14 and 15, the pressing mechanism 664 includes a movable claw 690 disposed along the diametral

diametrical direction of the fixing ring 674 of the substrate support section 662 and projecting inwardly from the fixing ring 674 for contacting the front surface of the substrate W. Positioned approximately at the center in the length direction of the movable claw 690, a pivot shaft 692 is provided on either side of the movable claw 690. The pivot shaft 692 is pivotably supported by a cover 696 which is mounted by bolts 694 to the lower surface of the fixing ring 674, so that the movable claw 690 can pivot vertically.